

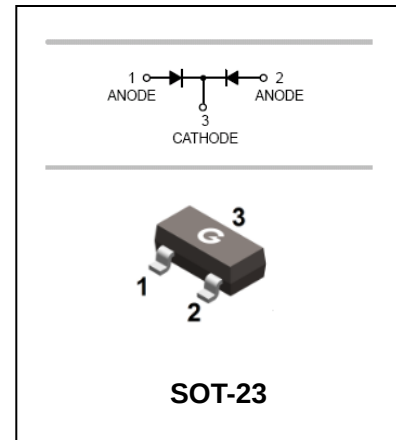
Dual Surface Mount Switching Diode

TBAV74

FEATURES

- For high-speed switching application
- Common cathode
- Halogen free
- Qualified to AEC-Q101 standards for high reliability

HF



APPLICATIONS

- Small signal switching

ORDERING INFORMATION

Type No.	Marking	Package Code
TBAV74	JA	SOT-23

MAXIMUM RATING @ Ta=25°C unless otherwise specified

Parameter	Symbol	Limits	Unit
Diode reverse voltage	V_R	50	V
Peak Reverse Voltage	V_{RM}	50	V
Forward Current	I_F	200	mA
Surge forward current, $t=1\mu s$	I_{FS}	4.5	A
Total Power Dissipation $T_s=35^\circ C$	P_{tot}	250	mW
Junction temperature	T_j	150	$^\circ C$
Storage temperature range	T_{stg}	-65 to +150	$^\circ C$

ELECTRICAL CHARACTERISTICS @ Ta=25°C unless otherwise specified

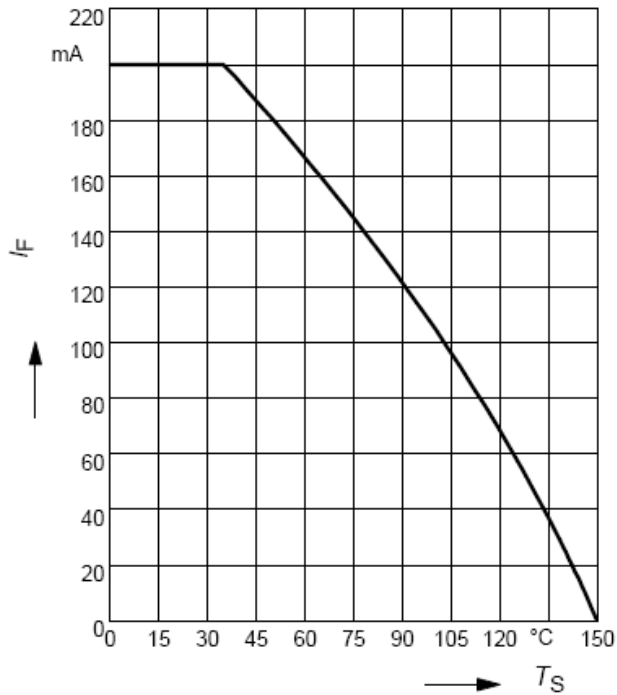
Parameter	Symbol	Test conditions	MIN	MAX	UNIT
Reverse breakdown voltage	$V_{(BR)R}$	$I_R=100\mu A$	50		V
Reverse voltage leakage current	I_R	$V_R=50V$ $V_R=50V T_A=150^\circ C$		0.1 100	μA
Forward voltage	V_F	$I_F=100mA$		1	V
Diode capacitance	C_D	$V_R=0V, f=1MHz$		2.0	pF
Reverse recovery time	t_{rr}	$I_F=I_R=10mA, R_L=100\Omega$		4	nS

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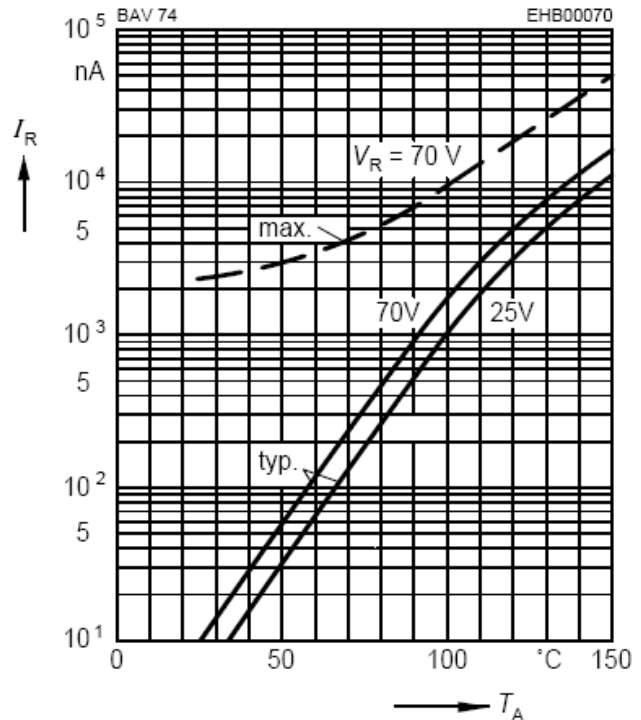
TBAV74

TYPICAL CHARACTERISTICS @ $T_a=25^\circ\text{C}$ unless otherwise specified

Forward current $I_F = f(T_S)$

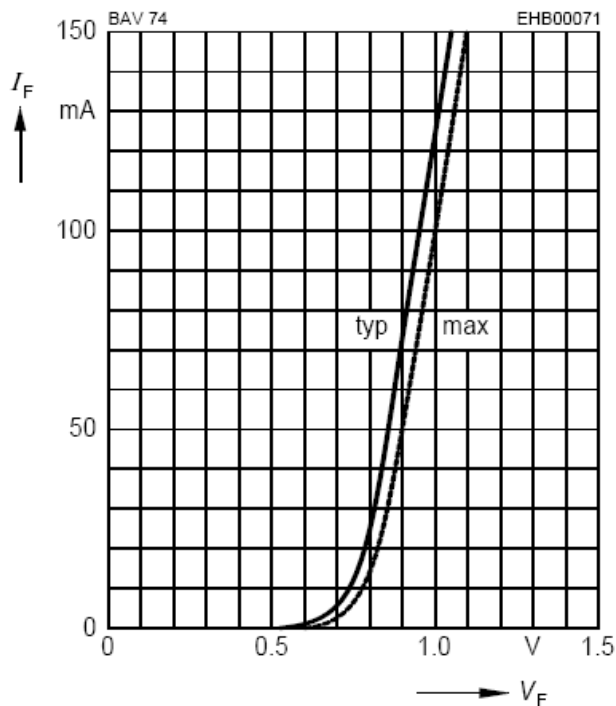


Reverse current $I_R = f(T_A)$



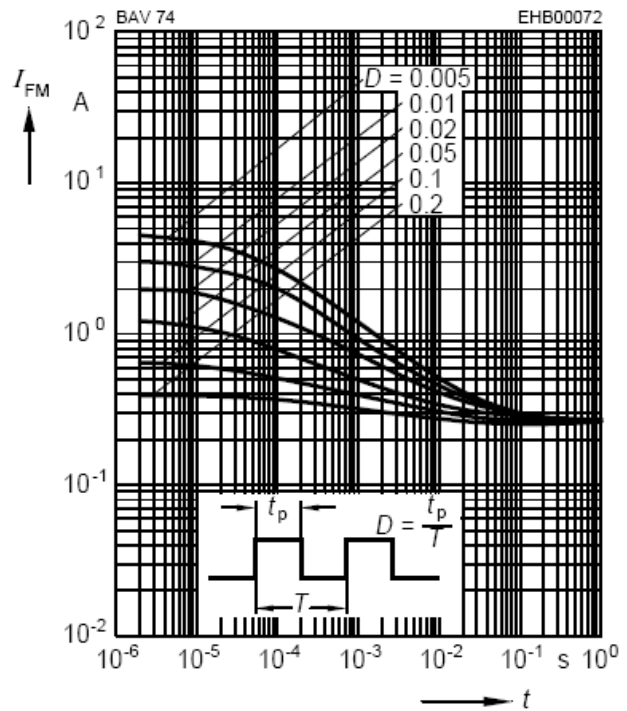
Forward current $I_F = f(V_F)$

$T_A = 25^\circ\text{C}$



Peak forward current $I_{FM} = f(t_p)$

$T_A = 25^\circ\text{C}$



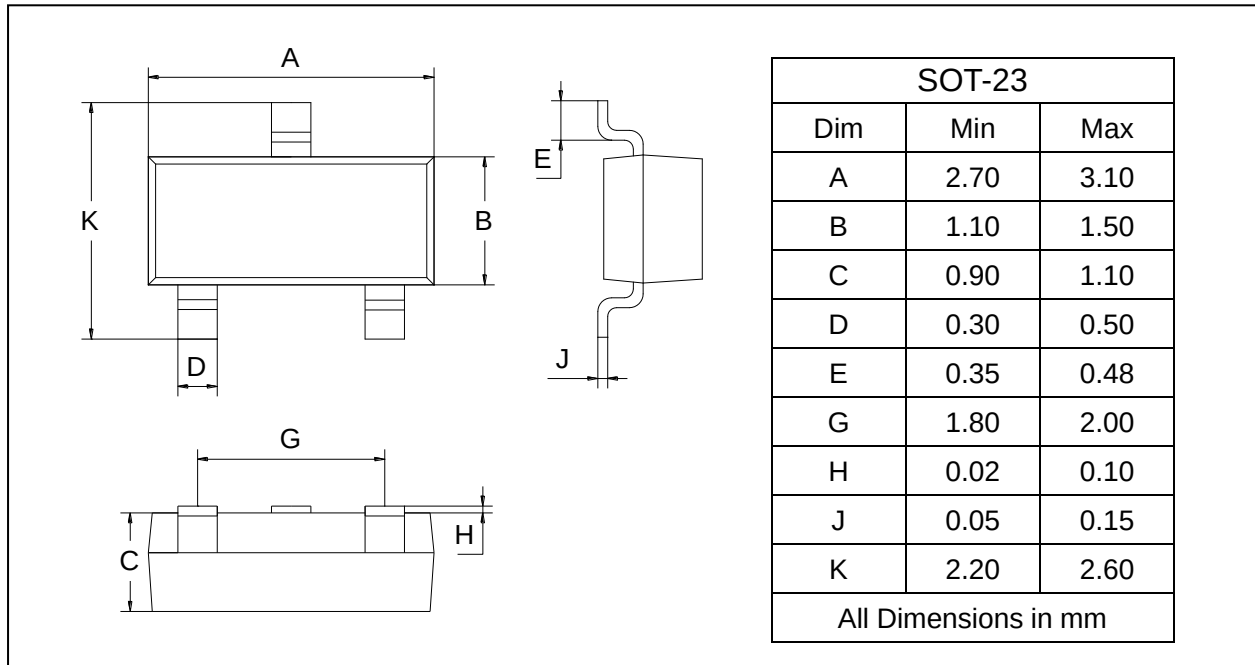
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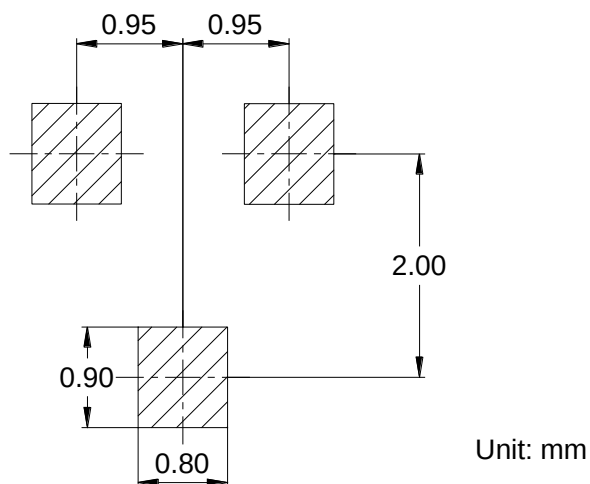
PACKAGE OUTLINE

Plastic surface mounted package

SOT-23



SOLDERING FOOTPRINT



PACKAGE INFORMATION

Device	Package	Shipping
TBAV74	SOT-23	3000 pcs / Tape & Reel